

### Features

- The plastic package carries UL Flammability Classification 94V-0
- For surface mounted applications
- Low power loss, high efficiency
- Built-in strain relief, ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed:260°C/10 seconds at terminals



### Mechanical Characteristics

- Case: SMB(DO-214AA) package molded plastic body
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- Mounting Position: Any
- Weight: 0.0034 ounce, 0.095 grams

### Absolute Maximum Ratings and Electrical Parameters (TA=25°C unless otherwise specified)

PARAMETER	SYMBOL	SS32	SS33	SS34	SS35	SS36	SS38	SS310	SS315	SS320	UNIT	
Maximum repetitive peak reverse voltage	$V_{RRM}$	20	30	40	50	60	80	100	150	200	V	
Maximum RMS voltage	$V_{RMS}$	14	21	28	35	42	56	70	105	140	V	
Maximum DC blocking voltage	$V_{DC}$	20	30	40	50	60	80	100	150	200	V	
Maximum average forward rectified current	$I_{AV}$	3									A	
Peak forward surge current <sup>(NOTE1)</sup>	$I_{FSM}$	80									A	
Maximum instantaneous forward voltage at 3A	$V_F$	0.55			0.7		0.85		0.9		V	
Maximum DC reverse current at rated DC blocking voltage	$T_A=25\text{ }^\circ\text{C}$	$I_R$					50		20		$\mu\text{A}$	
	$T_A=100\text{ }^\circ\text{C}$	$I_{RT}$					5000		2000		$\mu\text{A}$	
Typical junction capacitance <sup>(NOTE 2)</sup>	$C_J$	330			270						pF	
Typical Thermal Resistance Junction to Ambient <sup>(NOTE3)</sup>	$R_{\theta JA}$	65									$^\circ\text{C/W}$	
Typical Thermal Resistance Junction to Lead <sup>(NOTE3)</sup>	$R_{\theta JL}$	20									$^\circ\text{C/W}$	
Operating Temperature Range	$T_J$	-55 to 125					-55 to 150					$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 to 150									$^\circ\text{C}$	

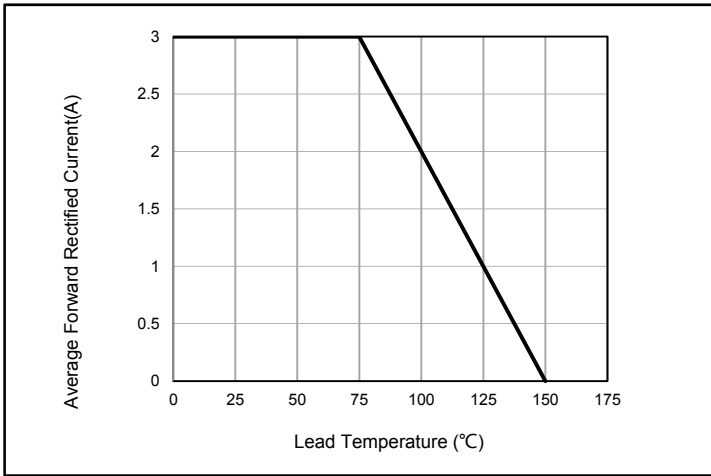
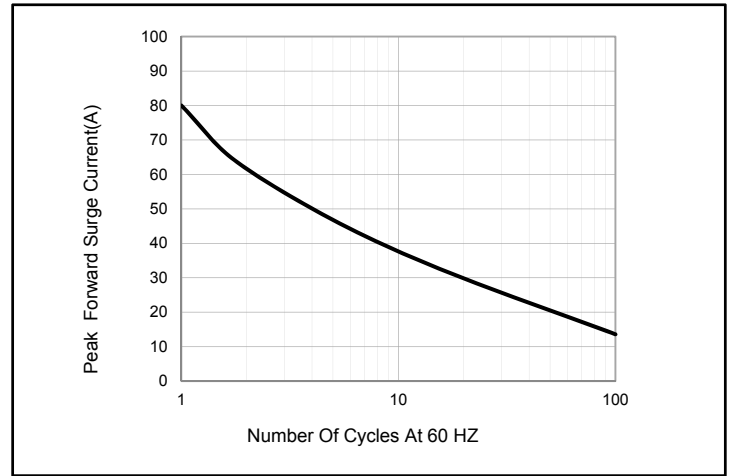
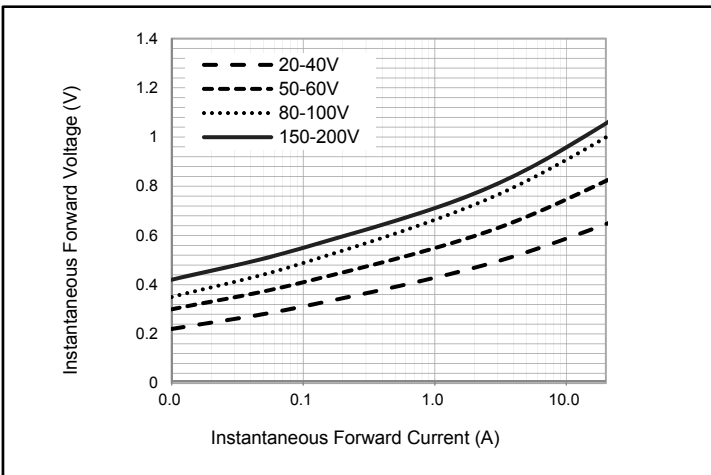
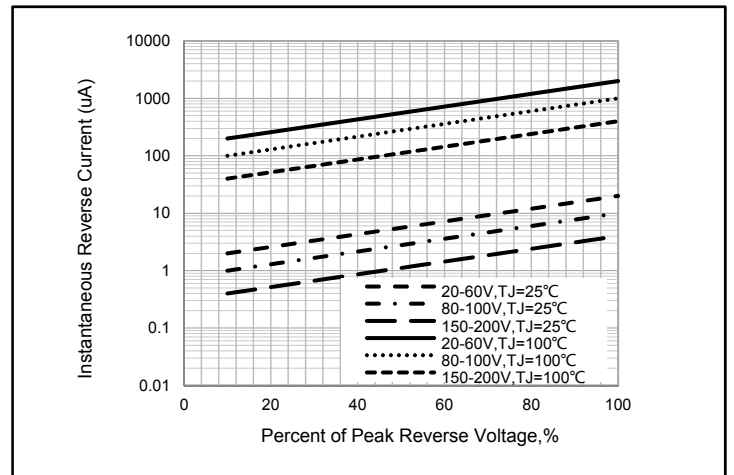
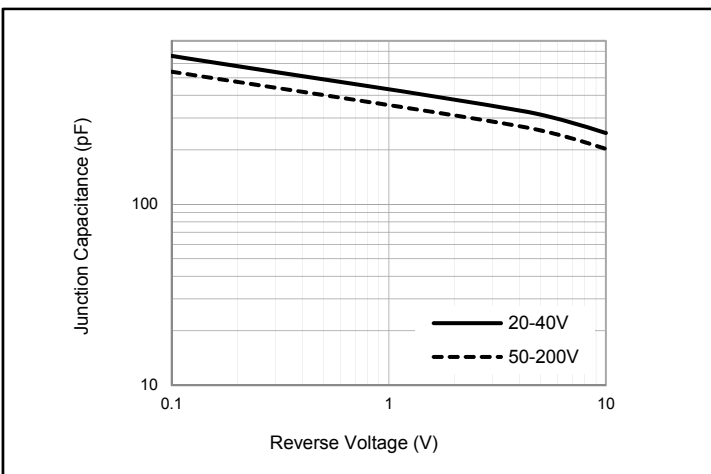
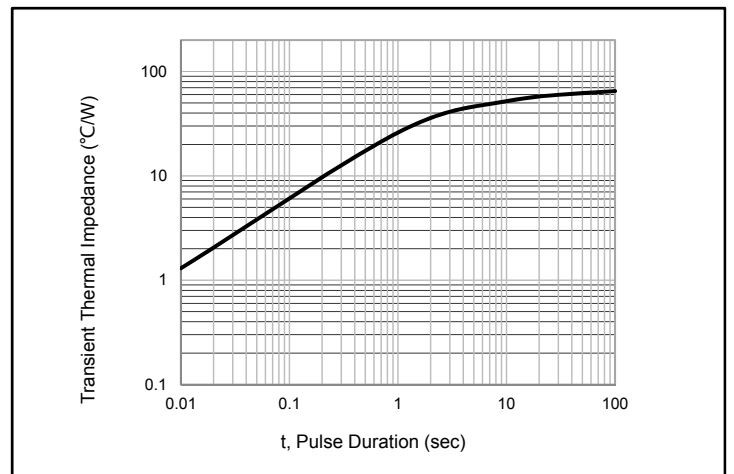
Note1: 8.3ms single half sine-wave superimposed on rated load

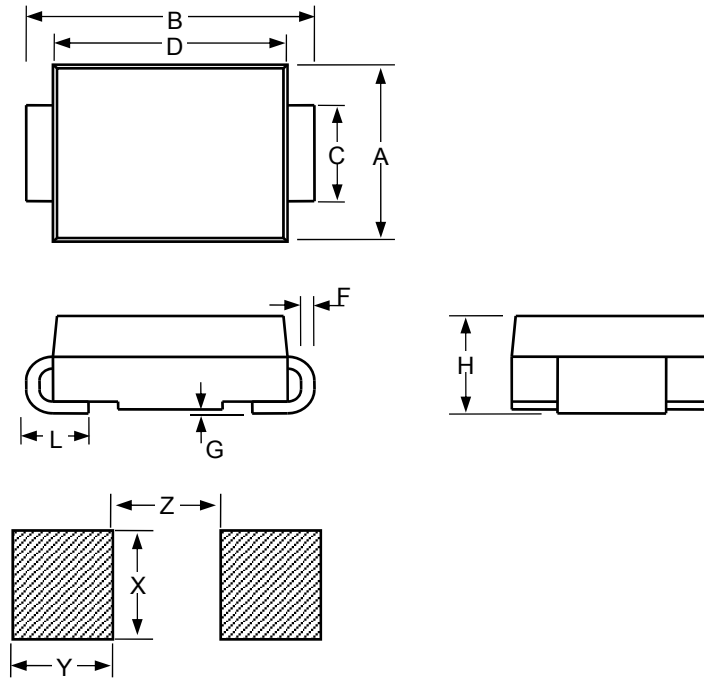
Note2: Measured at 1MHz and applied reverse voltage of 4.0V DC.

Note3: PCB. mounted with 7×7mm copper pad areas

### Summary of Packing Options

Package	Packing Description	Packing Quantity	Industry Standard
SMB	Tape/Reel, 13" reel	3000	EIA-481-1
	Tape/Reel, 7" reel	500	EIA-481-1

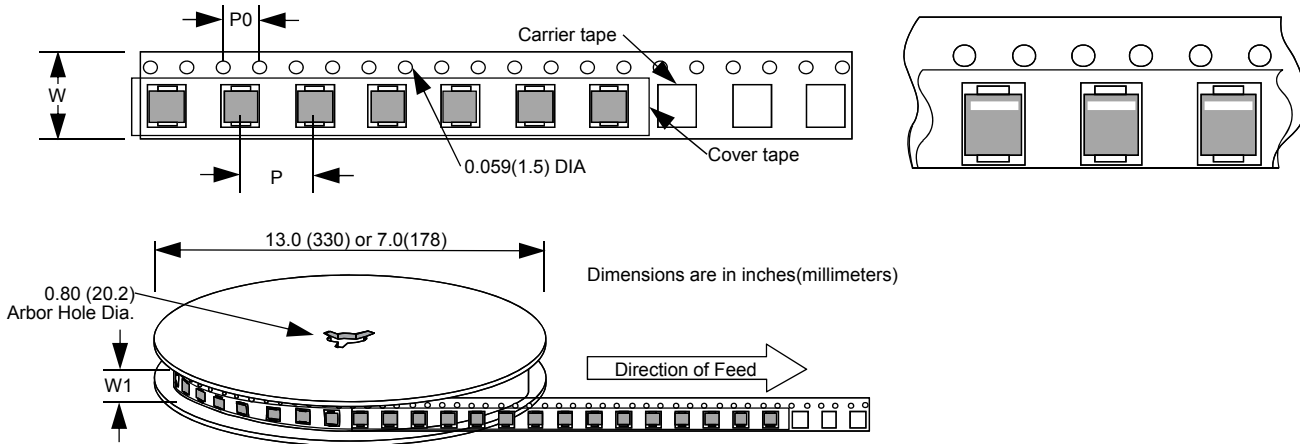

**Fig. 1 - Forward Current Derating Curve**

**Fig. 2 - Maximum Non-Repetitive Peak Forward Surge Current**

**Fig. 3 - Typical Instantaneous Forward Characteristics**

**Fig. 4 - Typical Reverse Characteristics**

**Fig. 5 - Typical Junction Capacitance**

**Fig. 6 - Typical Transient Thermal Impedance**



SMB						
Dimension	Inches			Millimeters		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.134	0.144	0.155	3.4	3.67	3.94
B	0.205	0.213	0.22	5.21	5.4	5.59
C	0.075	0.079	0.083	1.9	2	2.1
D	0.169		0.185	4.3		4.7
L	0.03		0.06	0.76		1.52
F	0.006		0.012	0.152		0.305
G	-		0.008	-		0.203
H	0.085	0.091	0.096	2.15	2.3	2.45
X		0.11			2.8	
Y		0.079			2	
Z		0.079			2	



Reflow Condition		Lead-free assembly
Pre Heat	- Temperature Min ( $T_{s(min)}$ )	150°C
	- Temperature Max ( $T_{s(max)}$ )	200°C
	- Time (min to max) ( $t_s$ )	60 – 180 secs
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak)		3°C/second max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/second max
Reflow	- Temperature ( $T_L$ ) (Liquidus)	217°C
	- Time ( $t_L$ )	60 – 150 secs
Peak Temperature ( $T_P$ )		260 <sup>+0/-5</sup> °C
Time within 5°C of actual peak Temperature ( $t_p$ )		20 – 40 secs
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (t)		8 minutes Max.
Do not exceed		260°C

**Tape and Reel Specification**


Dimension	Inches			Millimeters		
	MIN	NOM	MAX	MIN	NOM	MAX
P		0.315			8	
P0		0.157			4	
W		0.472			12	
W1		0.492			12.5	

**Disclaimer**

### Disclaimer

This document is for reference only, data sheet specifications and its information contained are intended to provide a product description only. Yfsemi Microelectronics Stock Co., Ltd. reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of with would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices). Customers using or selling Yfsemi components for use in such applications do so at their own risk and shall agree to fully indemnify Yfsemi and its subsidiaries harmless against all claims, damages and expenditures.

For additional information, please visit our website <http://www.yfsemi.com>

## X-ON Electronics

Largest Supplier of Electrical and Electronic Components

*Click to view similar products for [Schottky Diodes & Rectifiers](#) category:*

*Click to view products by [YFSEMI](#) manufacturer:*

Other Similar products are found below :

[MA4E2039](#) [MA4E2508M-1112](#) [MBR0530L-TP](#) [MBR10100CT-BP](#) [MBR1545CT](#) [MMBD301M3T5G](#) [RB160M-50TR](#)  
[BAS16E6433HTMA1](#) [BAS 3010S-02LRH E6327](#) [BAT 54-02LRH E6327](#) [IDL02G65C5XUMA1](#) [NSR05F40QNXT5G](#) [NSVR05F40NXT5G](#)  
[NTE555](#) [JANS1N6640](#) [SB07-03C-TB-H](#) [SK310-T](#) [SK33A-TP](#) [SK34B-TP](#) [SS3003CH-TL-E](#) [PDS3100Q-7](#) [GA01SHT18](#)  
[CRS10I30A\(TE85L,QM](#) [MA4E2501L-1290](#) [MBRB30H30CT-1G](#) [JANTX1N5712-1](#) [SB007-03C-TB-E](#) [SK33B-TP](#) [SK35A-TP](#) [SK38B-LTP](#)  
[NTE505](#) [NTSB30U100CT-1G](#) [VS-6CWQ10FNHM3](#) [CRG04\(T5L,TEMQ\)](#) [ACDBA1100LR-HF](#) [ACDBA1200-HF](#) [ACDBA240-HF](#)  
[ACDBA3100-HF](#) [CDBQC0530L-HF](#) [ACDBA260LR-HF](#) [ACDBA1100-HF](#) [MA4E2502L-1246](#) [10BQ015-M3/5BT](#) [10BQ060-M3/5BT](#)  
[NRVB130LSFT1G](#) [CRS08TE85LQM](#) [PMAD1108-LF](#) [B120Q-13-F](#) [1N5819T-G](#) [B0530WSQ-7-F](#)